Brazing alloy BrazeTec 4404

Composition (% in weight)

<table>
<thead>
<tr>
<th>Ag</th>
<th>Cu</th>
<th>Zn</th>
<th>Sn</th>
<th>Si</th>
<th>P</th>
<th>Mn</th>
<th>Ni</th>
<th>Other</th>
<th>ISO 17672:2010</th>
<th>EN 1044:1999</th>
<th>ISO 3677</th>
</tr>
</thead>
<tbody>
<tr>
<td>44</td>
<td>30</td>
<td>26</td>
<td>-</td>
<td>-</td>
<td>-</td>
<td>-</td>
<td>-</td>
<td>-</td>
<td>AG 203</td>
<td>-</td>
<td></td>
</tr>
</tbody>
</table>

Technical data:

- **Melting range (°C)**: 675 - 735
- **Working temperature (°C)**: 730
- **Melting range according to DSC measurement (°C)**: -
- **Min. brazing temperature (°C)**: -
- **Electrical conductivity (m/Ω mm²)**: 11,2
- **Elongation %**: 25
- **Density (g/cm³)**: 9,1
- **Shear strength (MPa)**: -
- **Tensile strength DIN EN 12797 (MPa)**: with S 235:400; with E 295:480
- **Operating temperature of brazed joint (min/max) ± (°C)**: 200

Applications
Air conditioning, refrigeration and electrical industry, plumbing technology, automotive, spectacle frames (optics), precision metal parts, fashion accessories, tool industry

Operating conditions
Silver based brazing alloy with excellent flow, capillarity and mechanical strength characteristics. Used for brazing any steels, copper and copper alloys, as well as nickel and nickel alloys.

Recommended fluxes

Heat sources
Induction heating, flame, furnace in vacuum and under protective atmosphere

Delivery forms
Wire, rods, ribbon, rings, preforms, powder

Notes
Brazetec 4404 is approved and registered by DVGW, as meets the requirements of the working sheet "GW2" and "GW 7" of DVGW (German Association of Gas and Water).
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